

FIG. 1A is a schematic diagram of a device 100 in a first state. The device 100 includes a substrate 110, a first layer 120, a second layer 130, and a third layer 140. The first layer 120 is disposed on the substrate 110, and the second layer 130 is disposed on the first layer 120. The third layer 140 is disposed on the second layer 130. The device 100 is shown in a perspective view, and the layers 110, 120, 130, and 140 are shown in cross-section. The first layer 120 is a thin layer, and the second layer 130 is a thicker layer. The third layer 140 is a thin layer. The device 100 is shown in a perspective view, and the layers 110, 120, 130, and 140 are shown in cross-section. The first layer 120 is a thin layer, and the second layer 130 is a thicker layer. The third layer 140 is a thin layer.

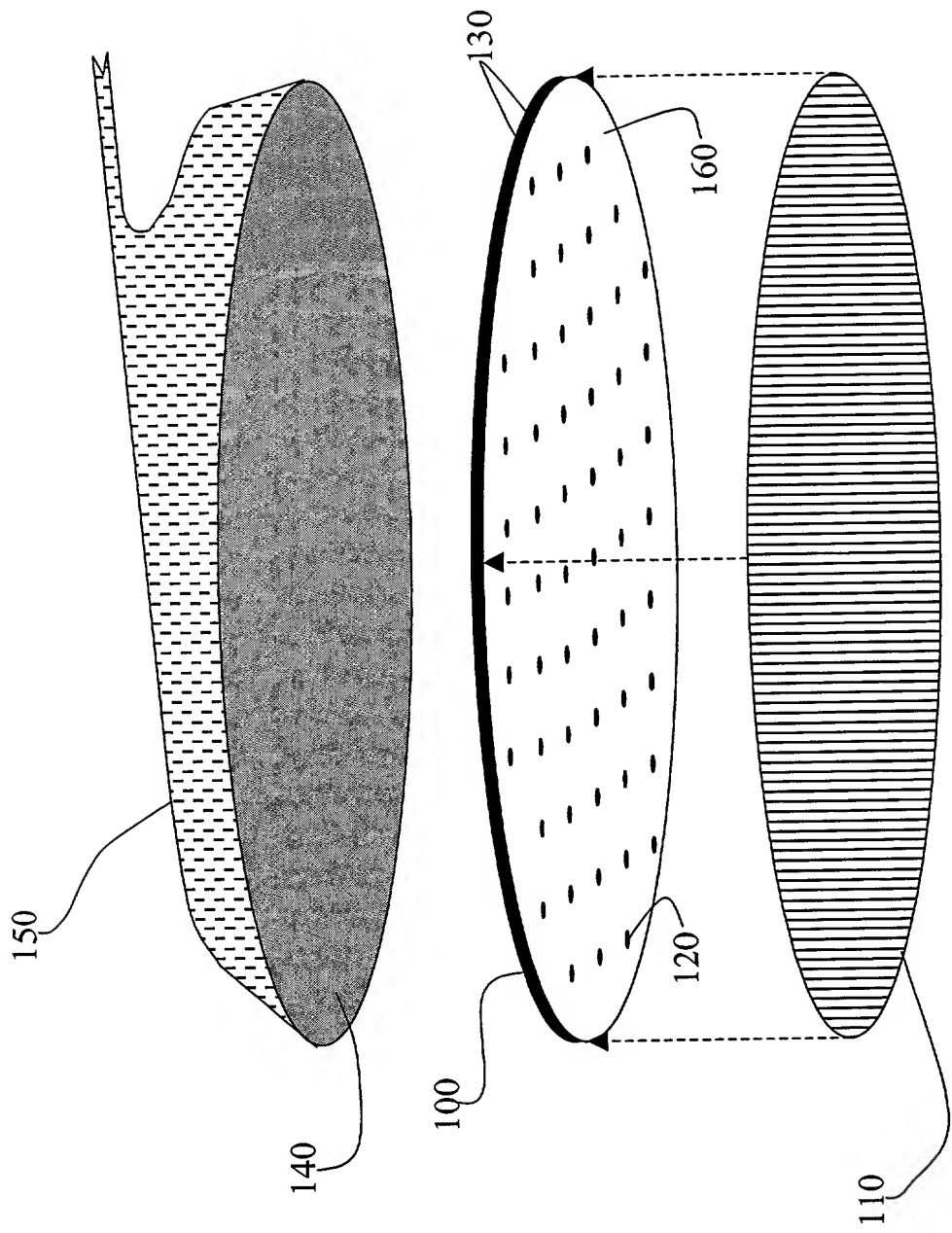
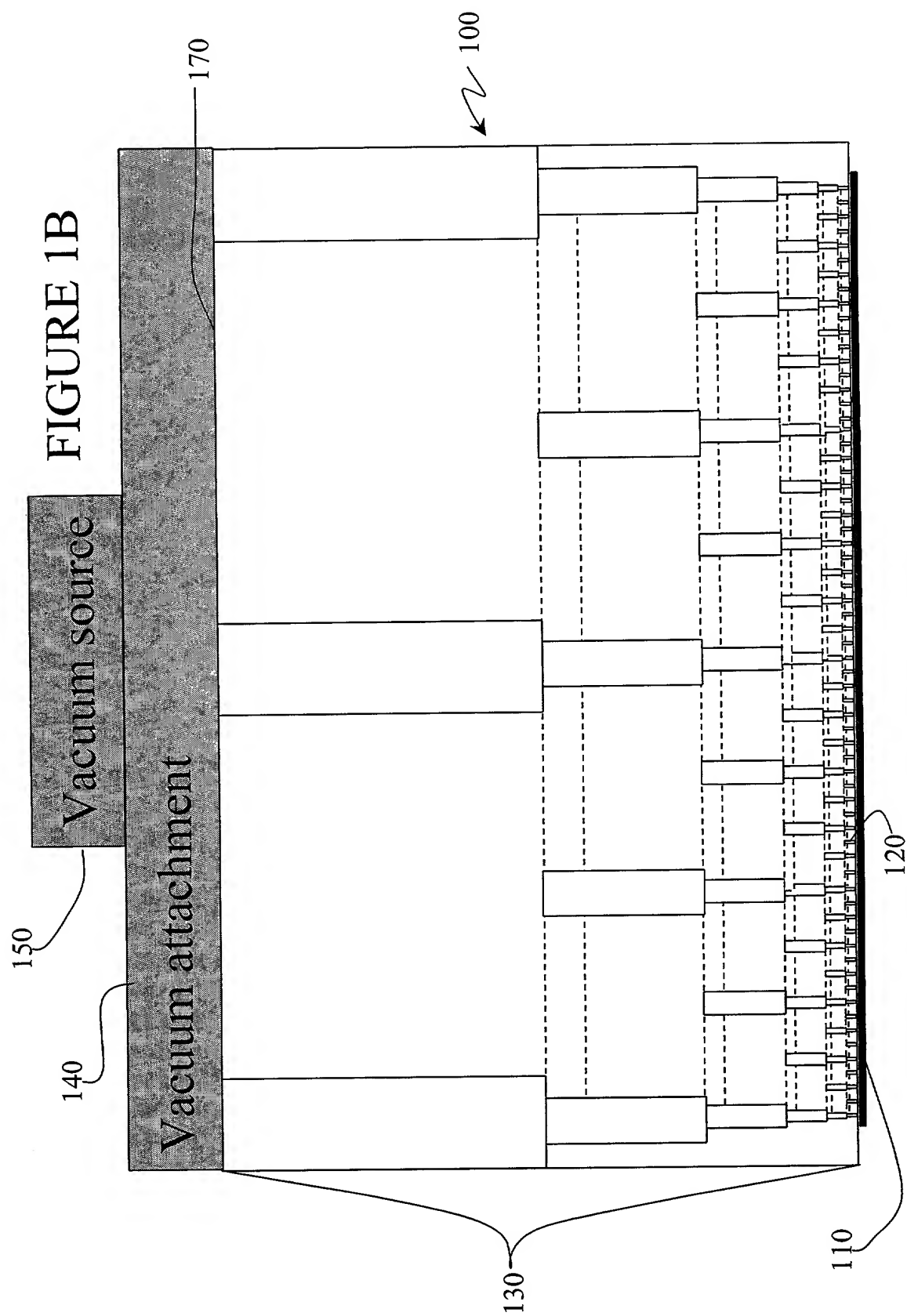


FIGURE 1A

FIGURE 1B



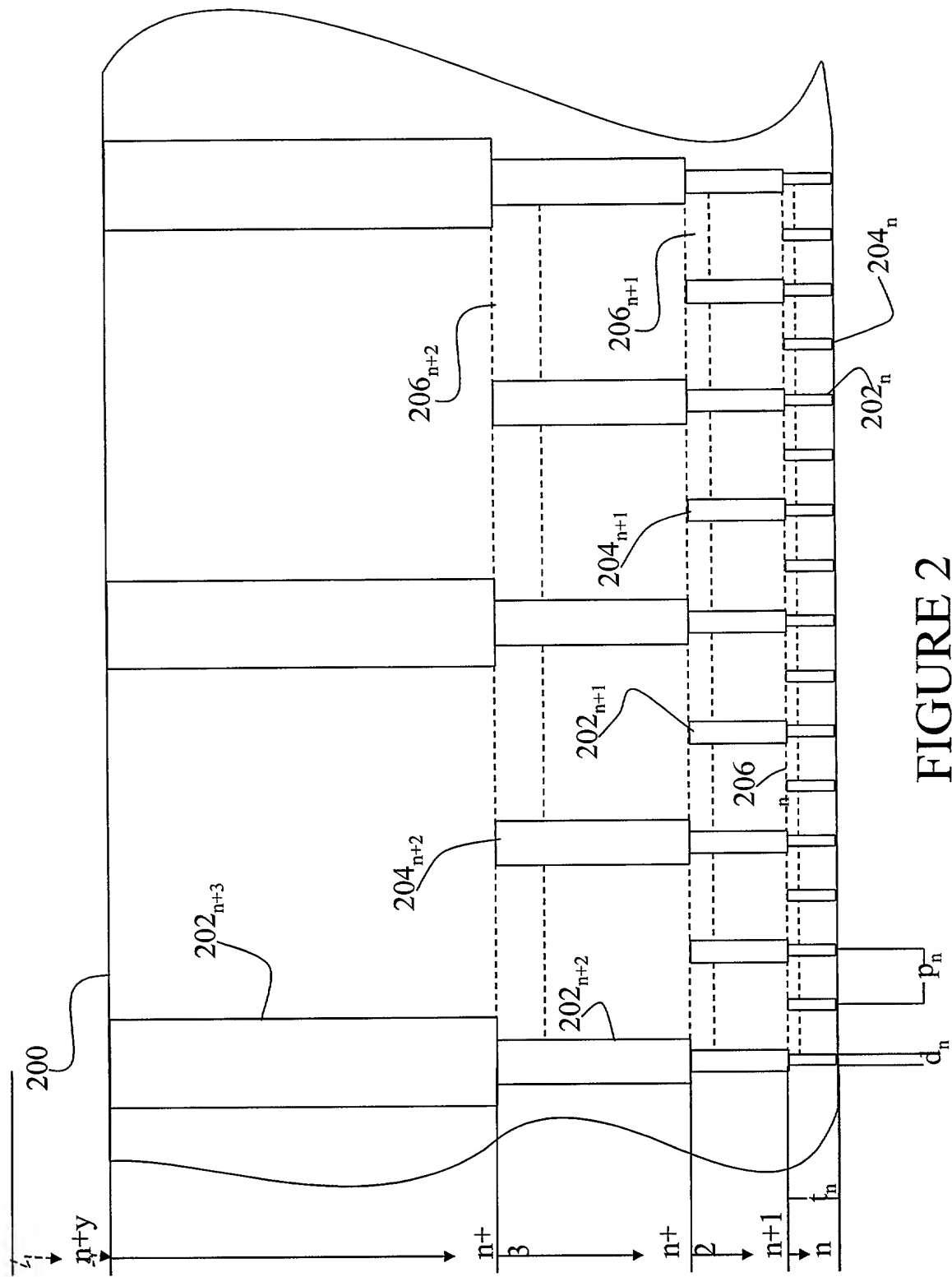


FIG. 3A is a schematic diagram of a grid structure 200. The grid structure 200 includes a grid of elements 202_n and 204_n. The elements 202_n are arranged in a grid pattern, and the elements 204_n are arranged in a grid pattern. The grid structure 200 is shown in a perspective view.

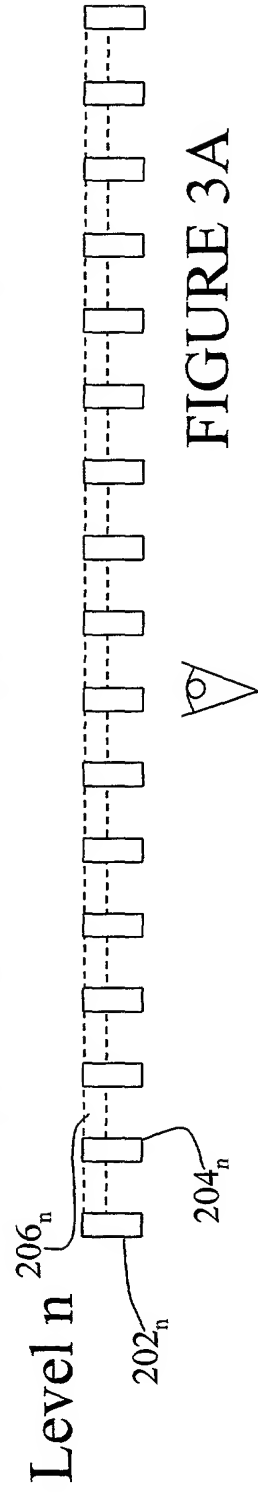
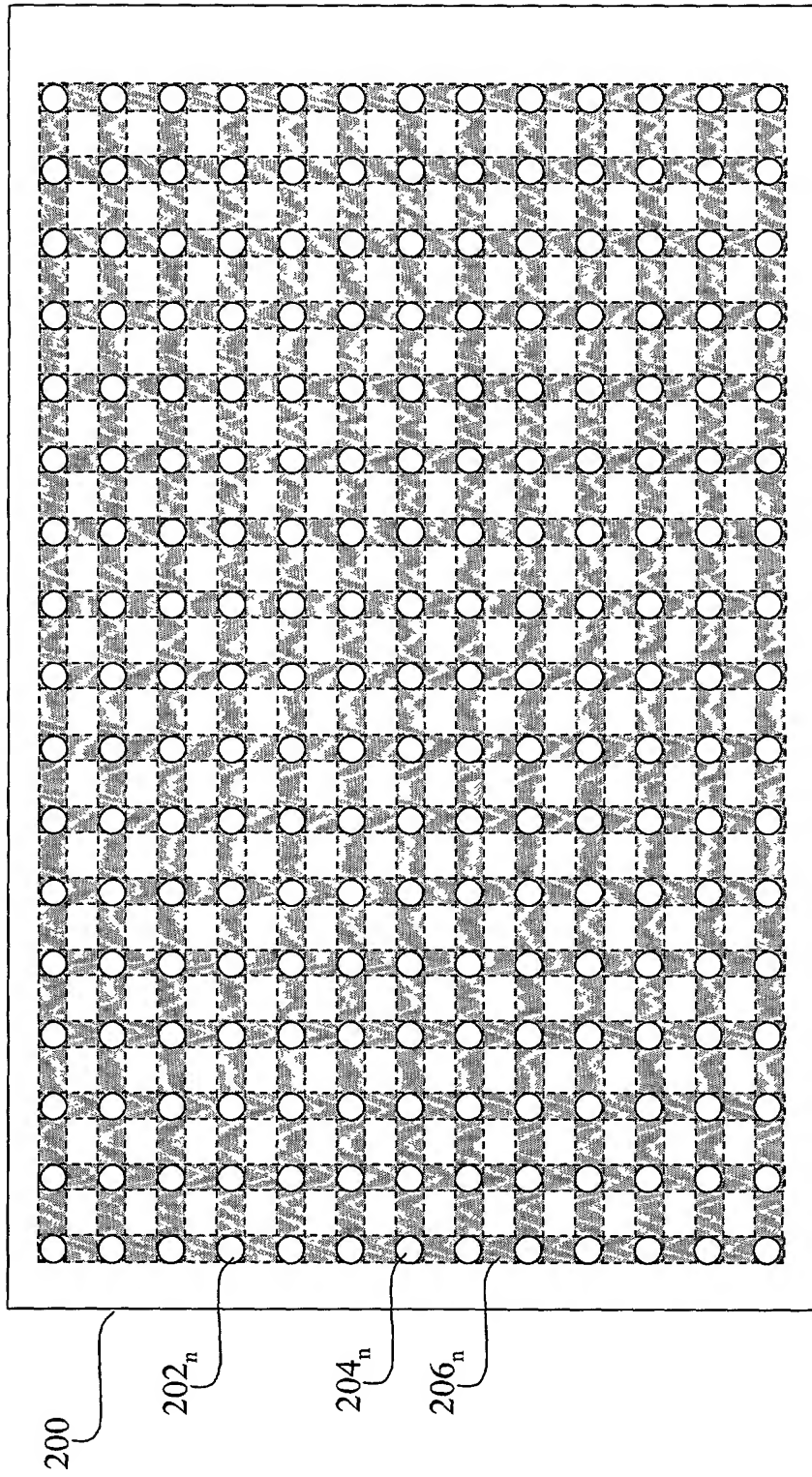


FIGURE 3A

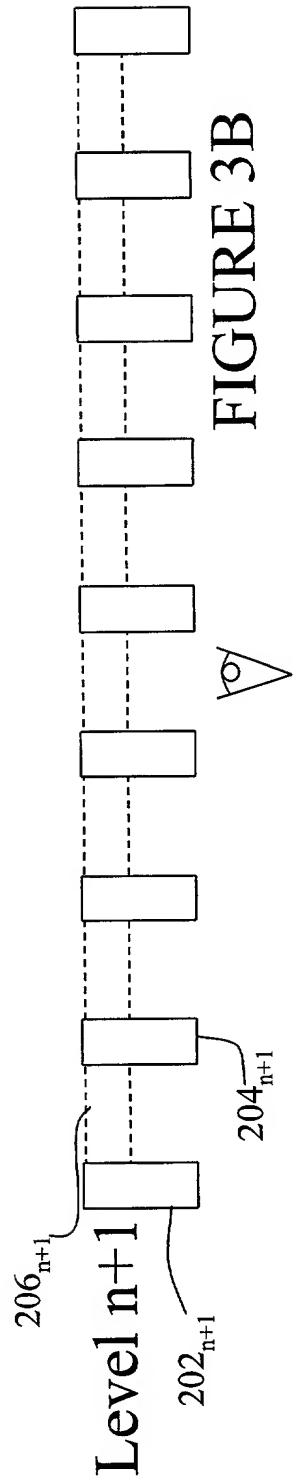
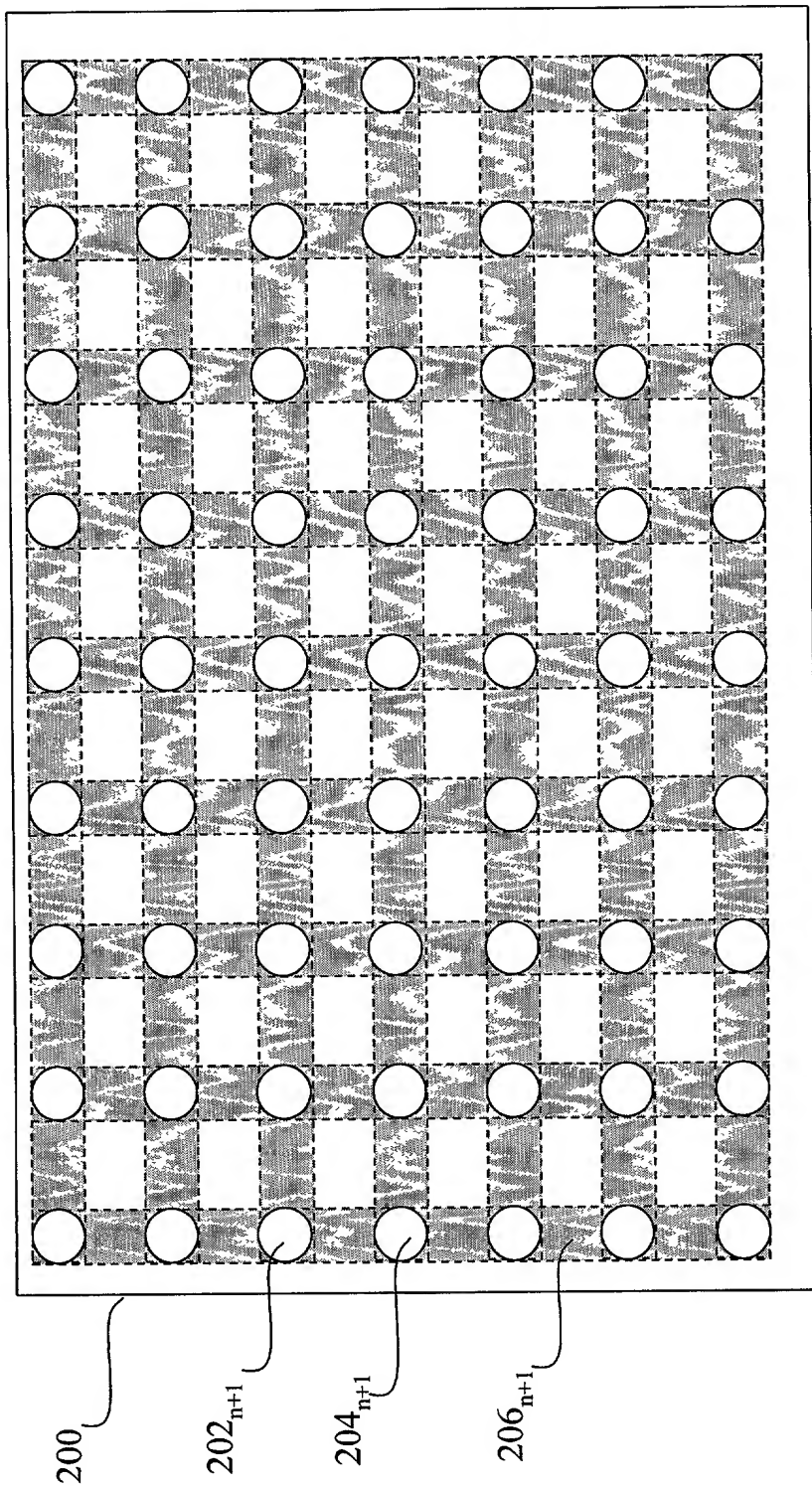


FIGURE 3B

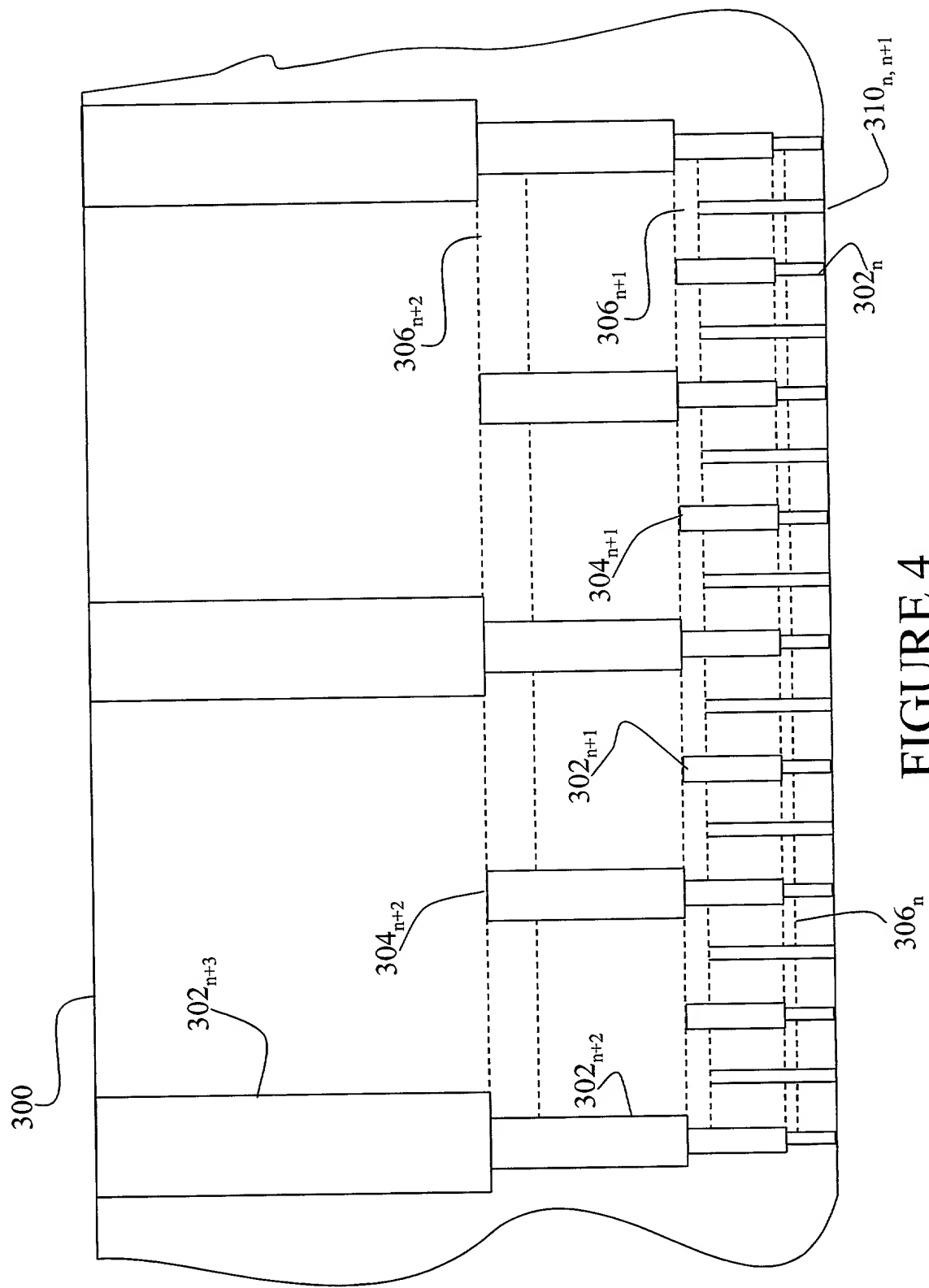


FIGURE 4

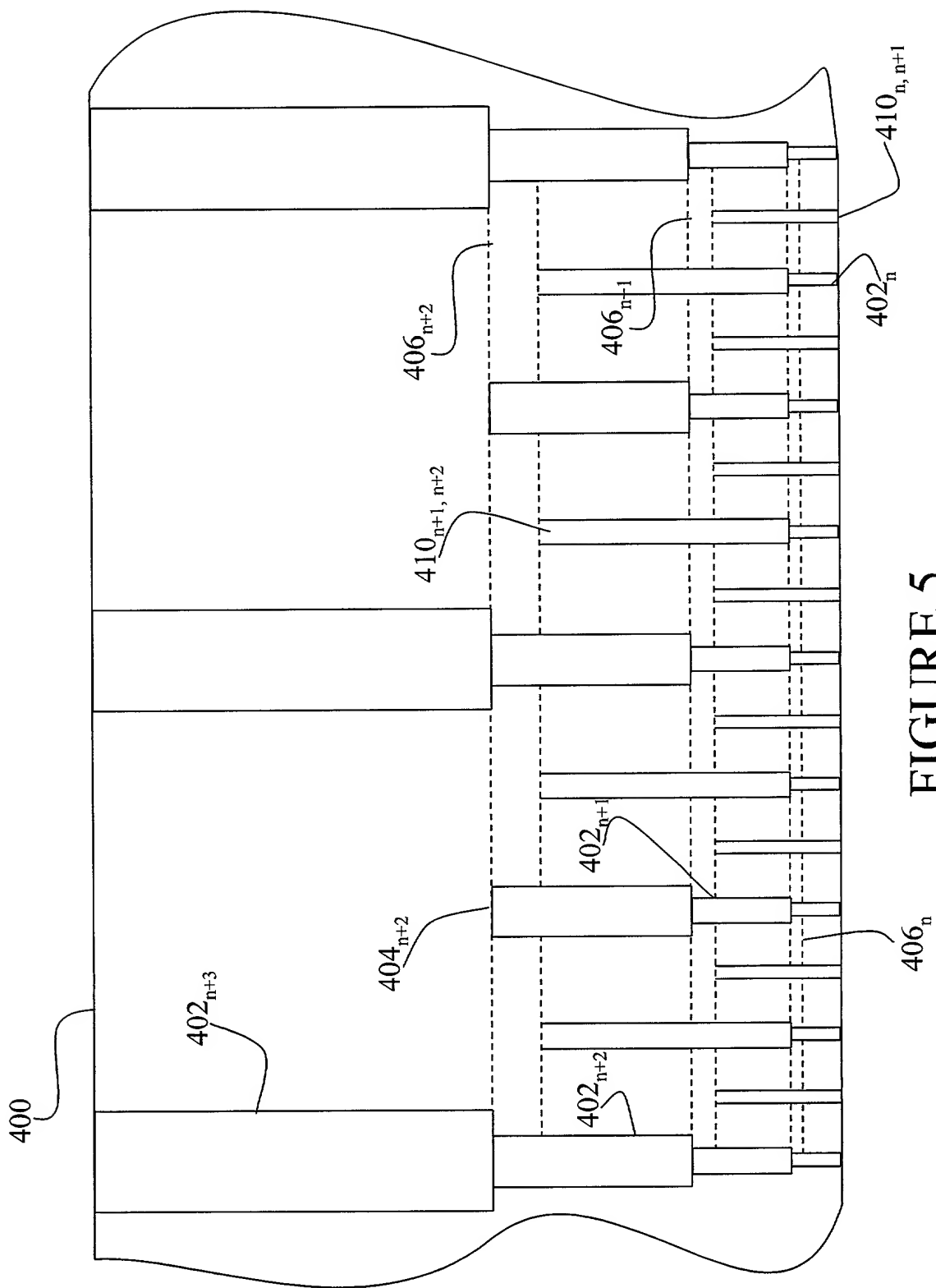


FIGURE 5

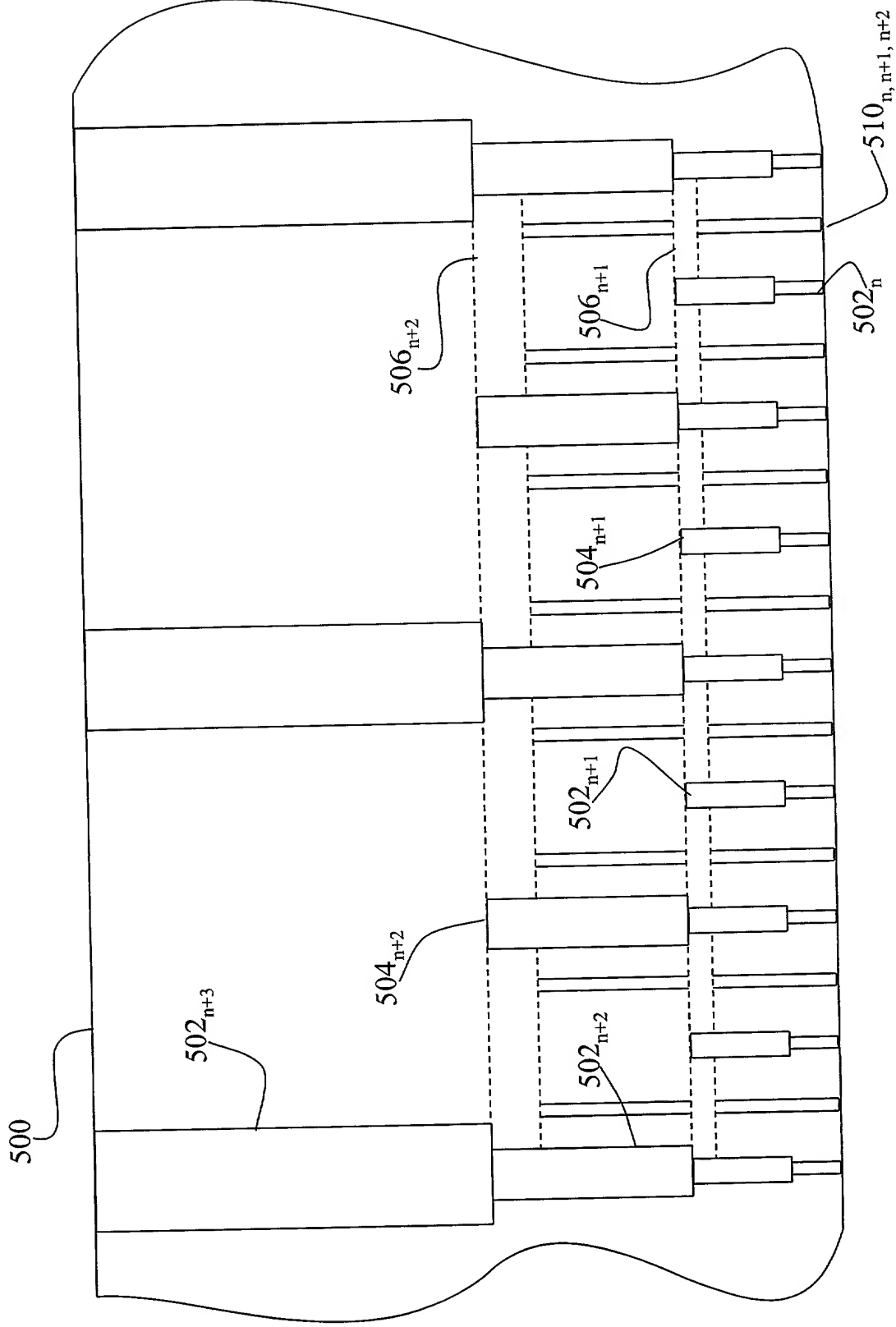


FIGURE 6

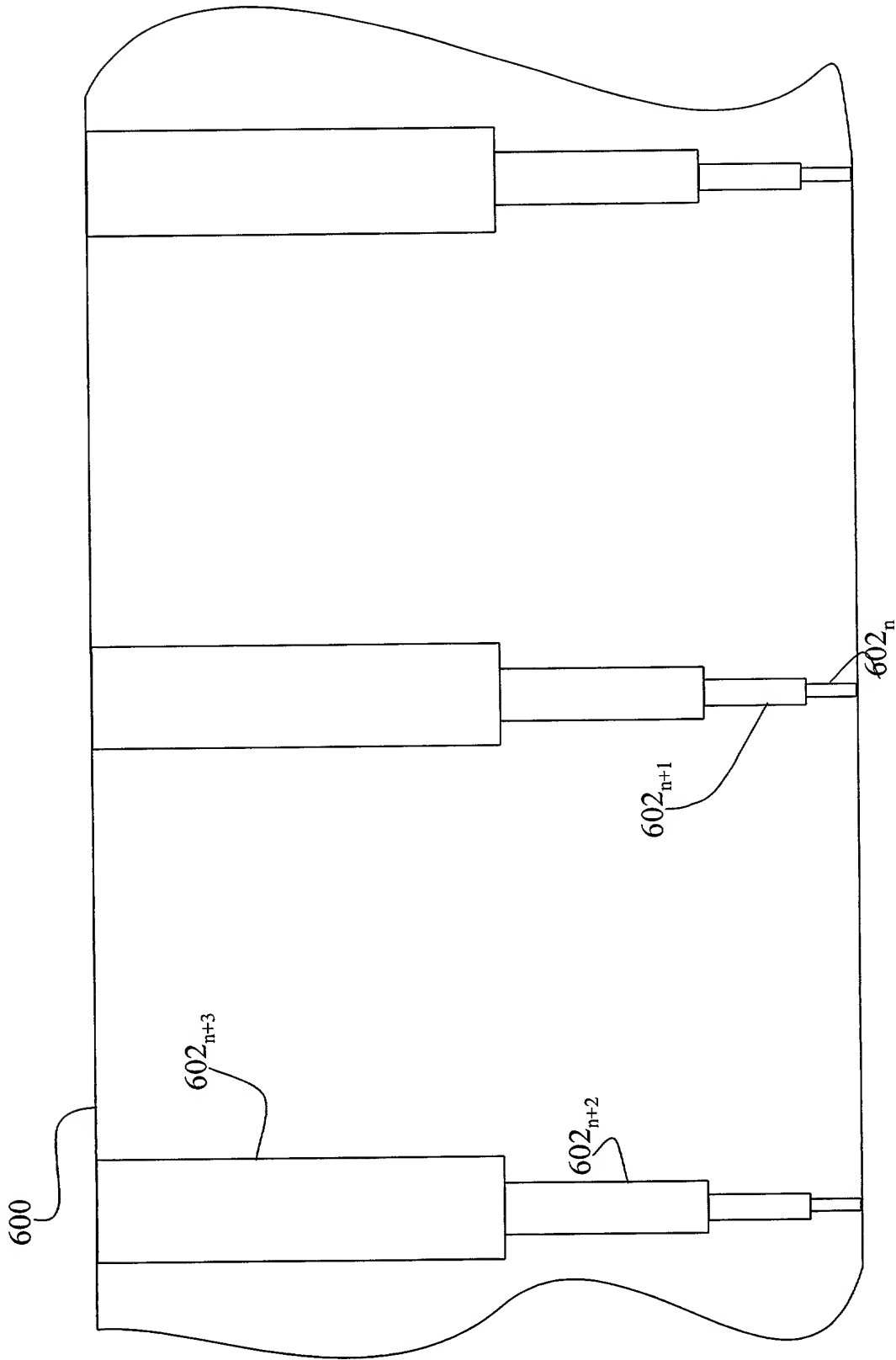


FIGURE 7

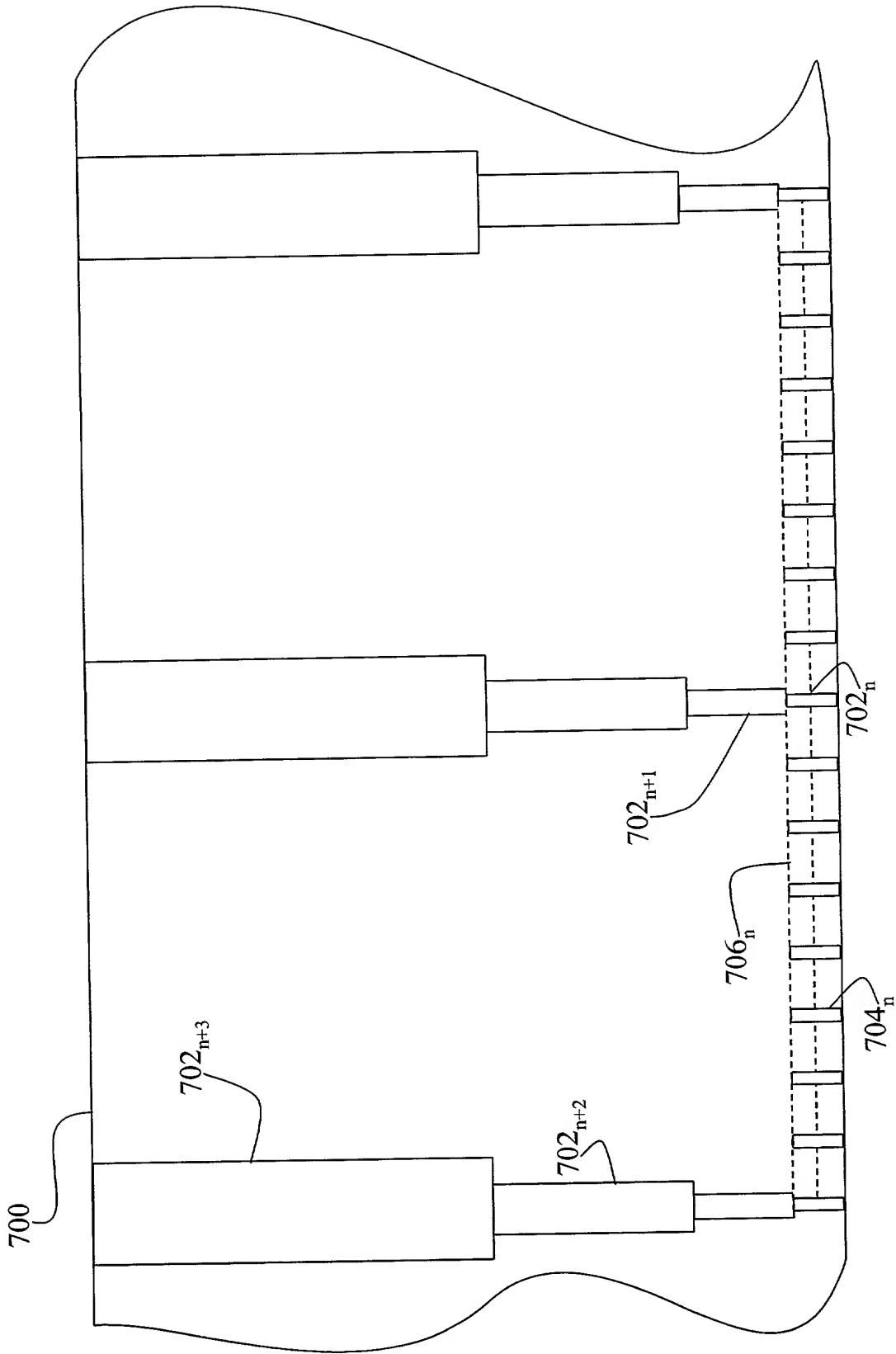


FIGURE 8

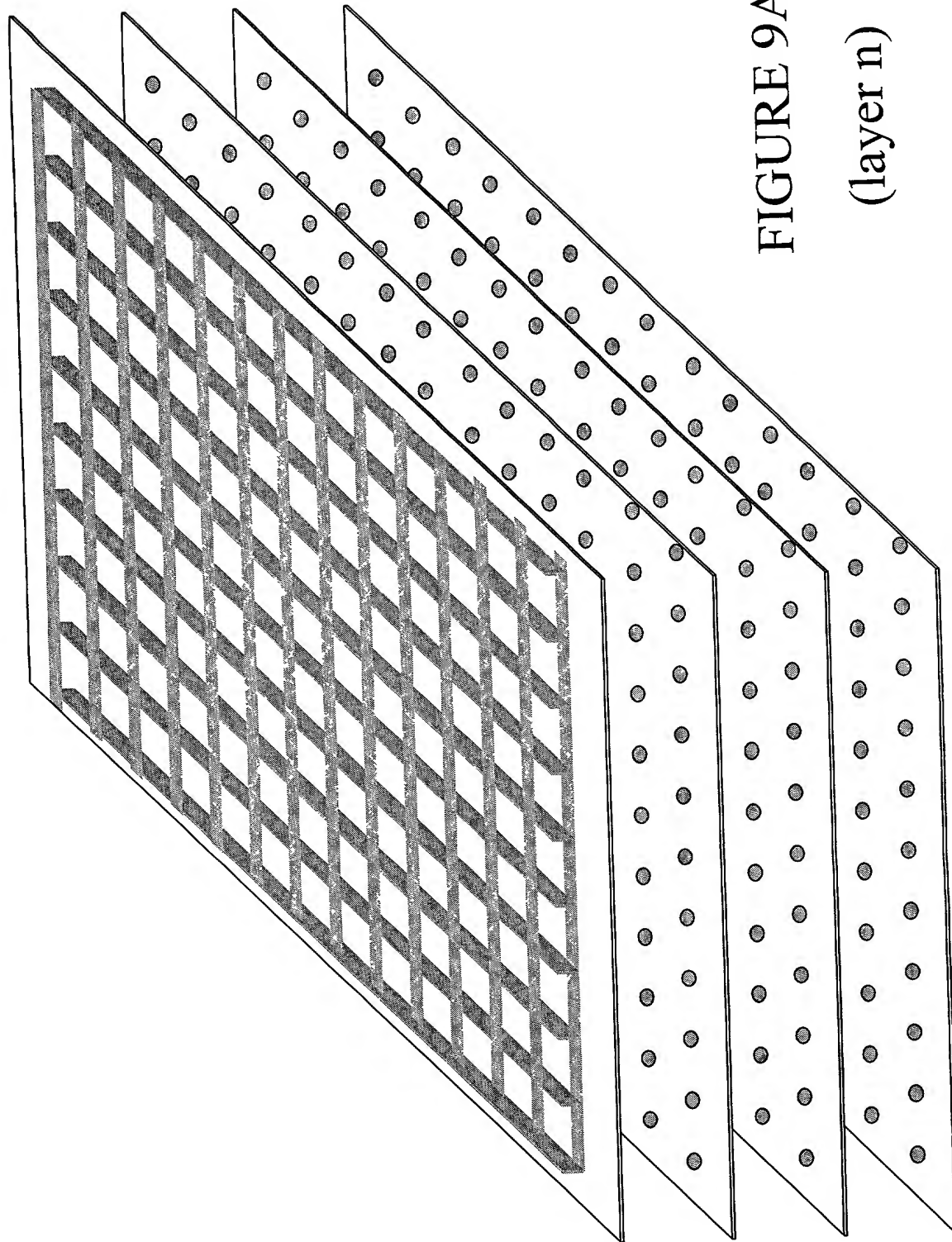


FIGURE 9A
(layer n)

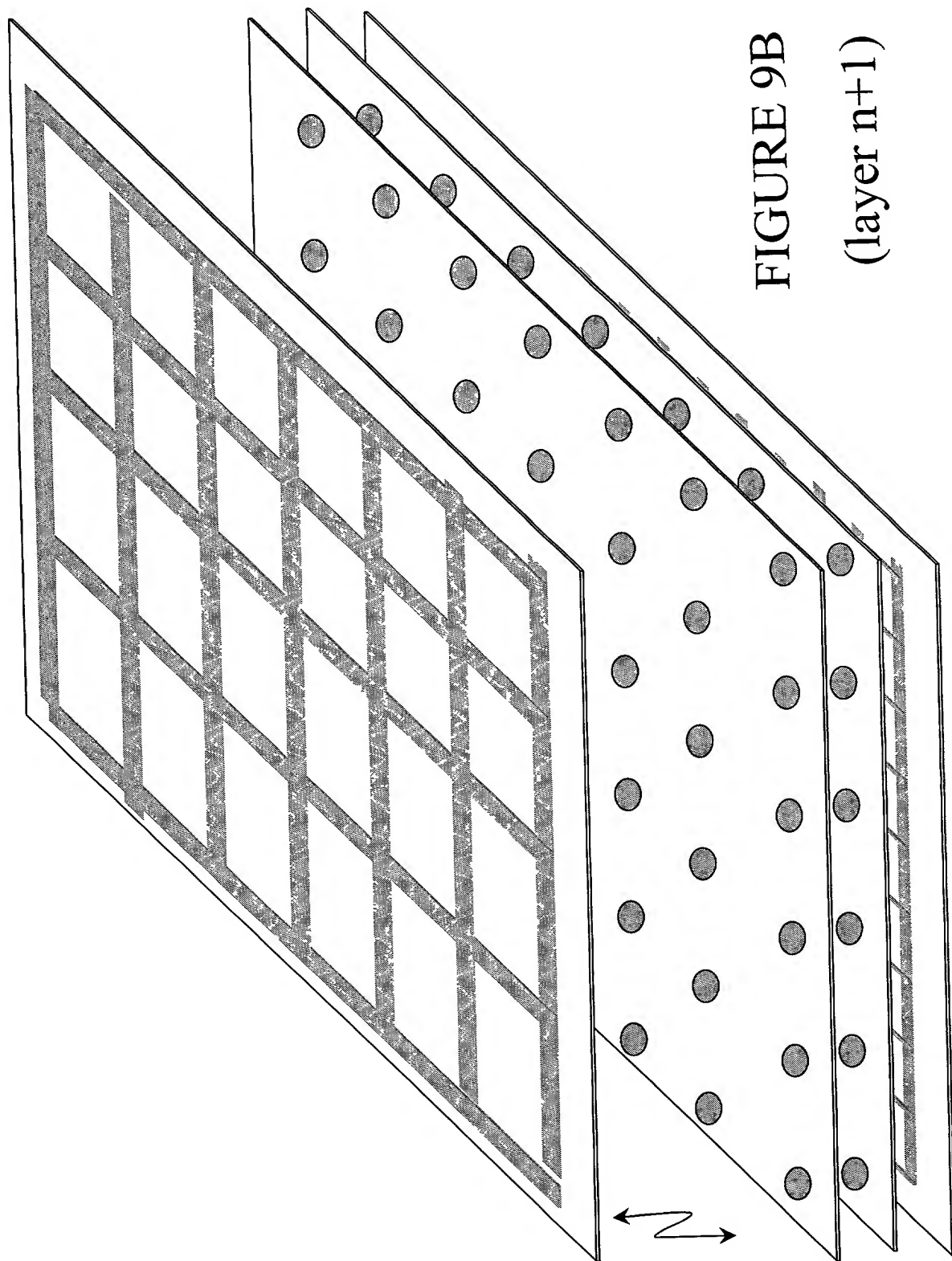


FIGURE 9B
(layer n+1)

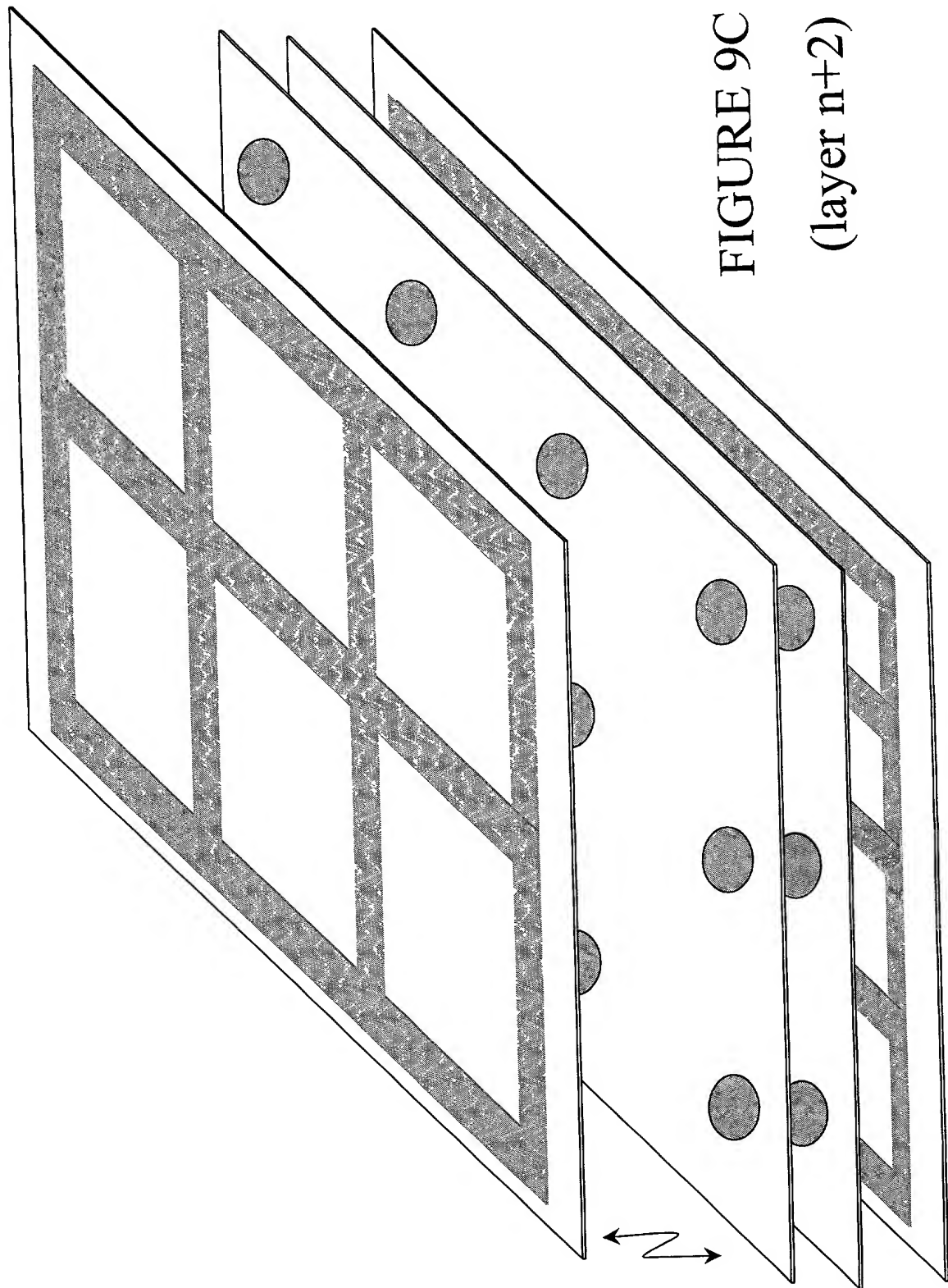


FIGURE 9C
(layer $n+2$)

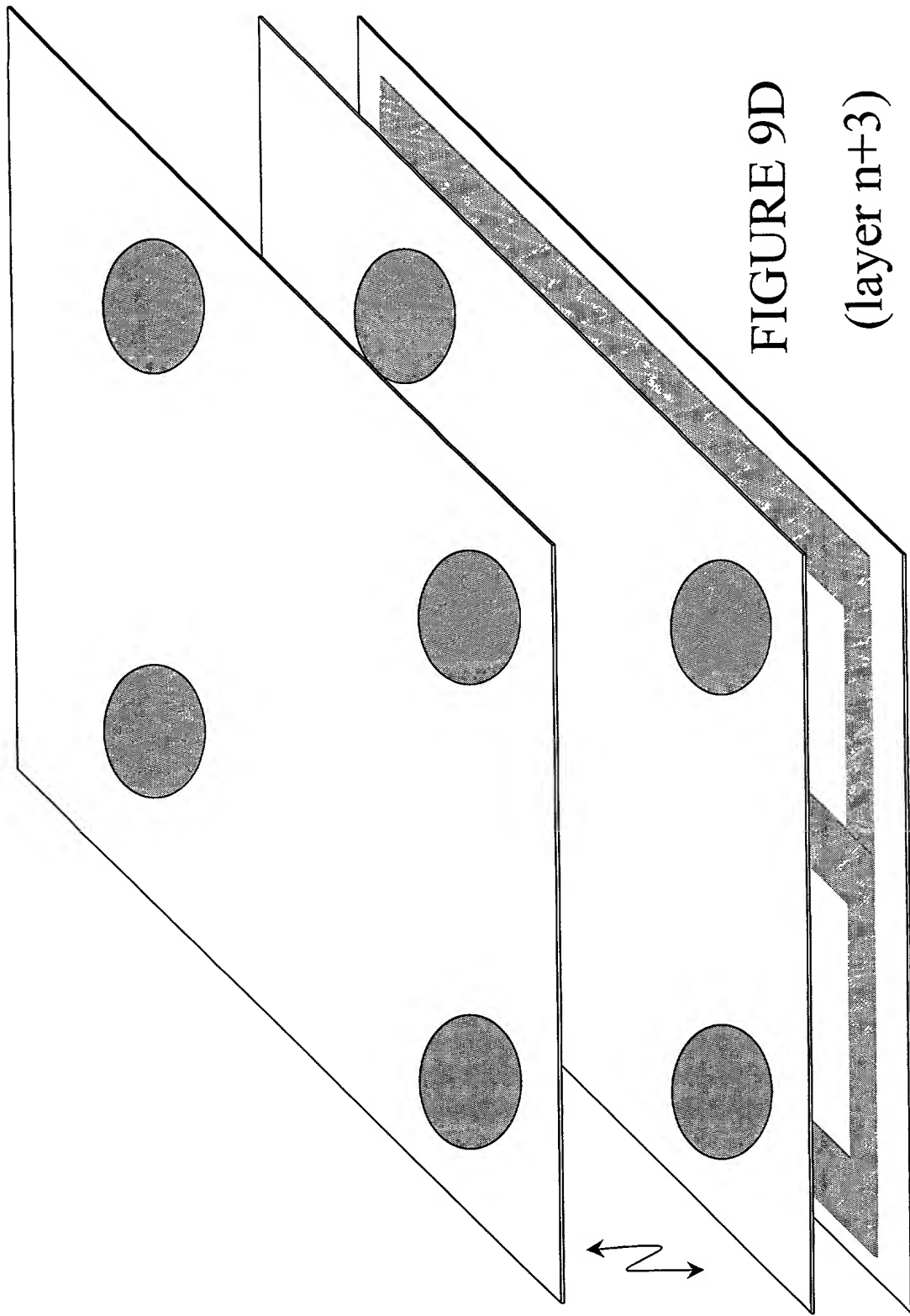
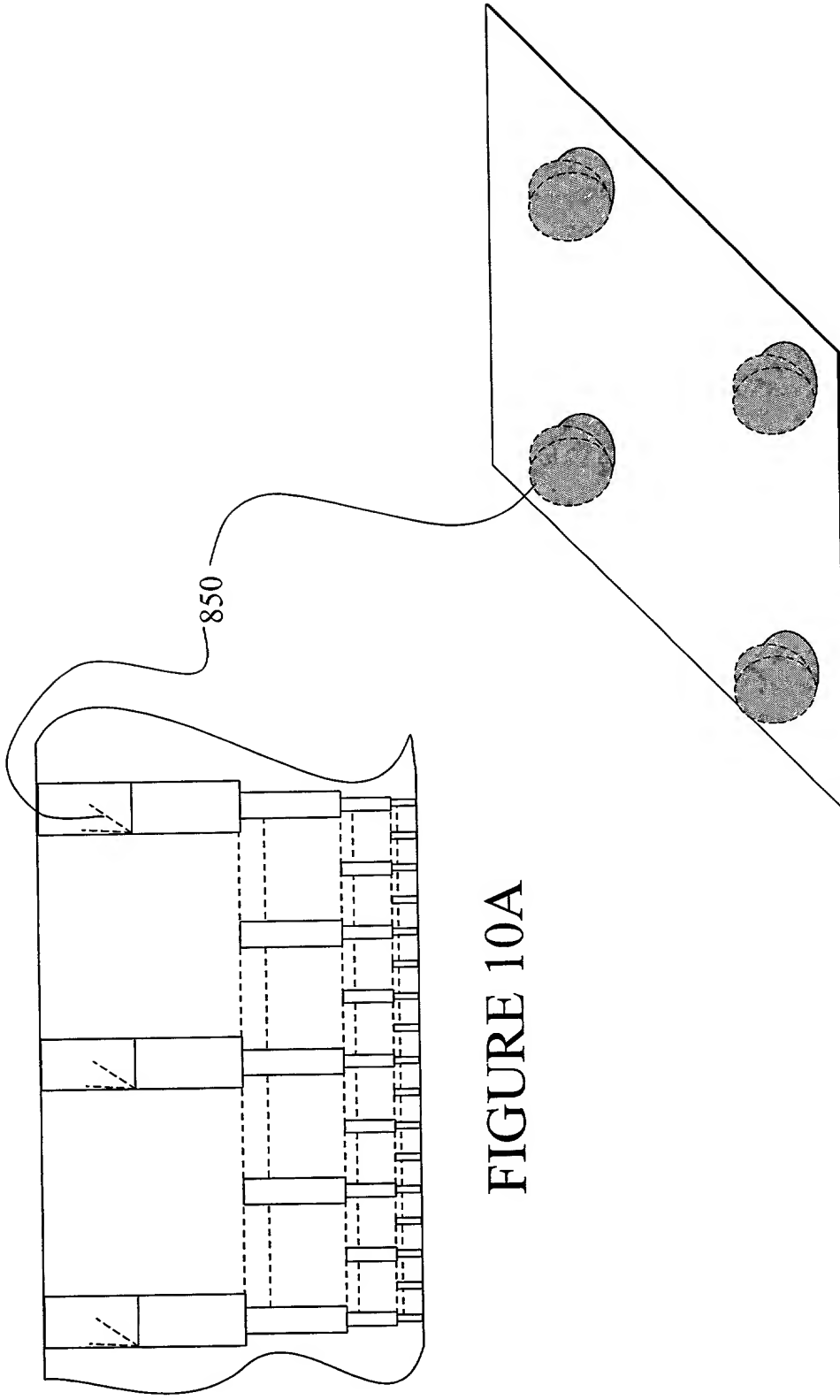


FIGURE 9D
(layer $n+3$)



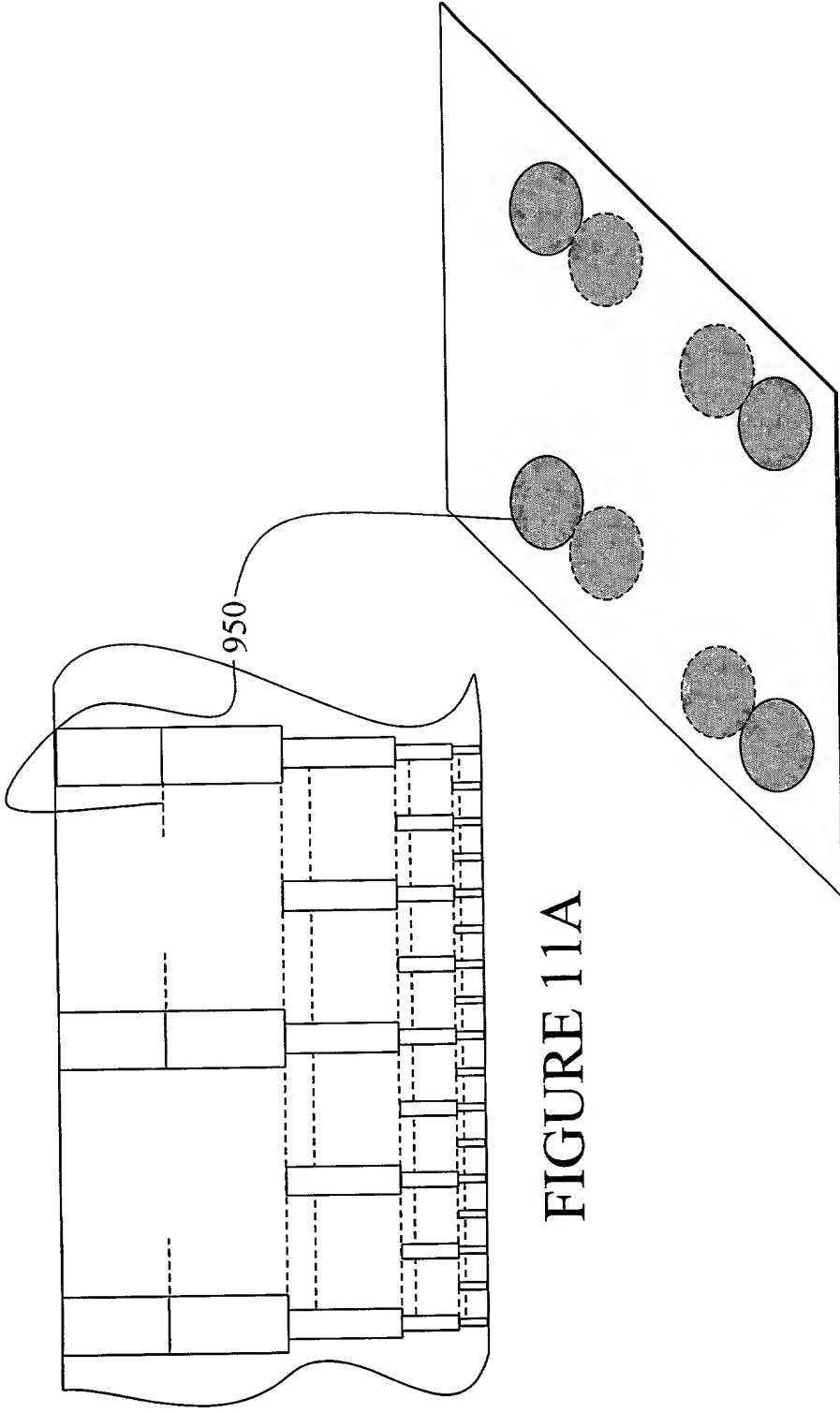


FIGURE 11A

FIGURE 11B